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(54) Title: COOLING A COMPUTER PROCESSING UNIT

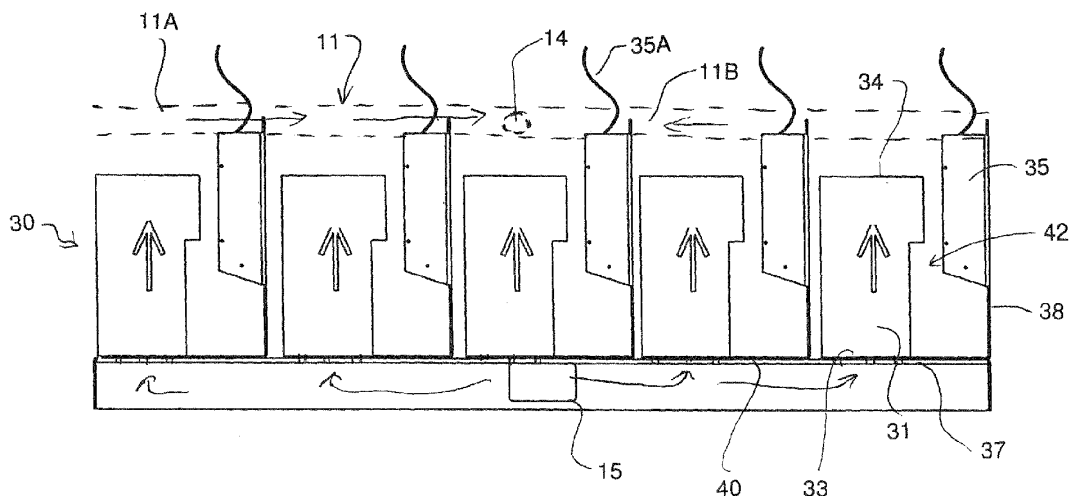


FIG. 6

(57) Abstract: Computer processing systems are cooled and the otherwise wasted heat is extracted for space heating by providing a cooling dielectric liquid in a tank which passes from a manifold at the bottom of the tank through an array of tubular housings each having open top and bottom ends and containing row of the circuit boards. The housings sit on a divider sheet which has arrays of openings aligned with the housings allowing the liquid to pass from the manifold under little or no pressure so that the liquid flows through the housings by convection and stratifies to generate a layer of heated liquid above the open tops of the housings which can be tapped off to a heat exchanger. The liquid around the housings is not fed from the manifold and the power supplies for the circuit boards sit in this body of liquid and are cooled thereby.

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